

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT6646581

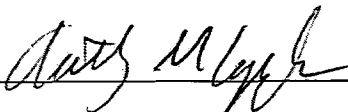
SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ANTHONY M. COPPOLA	03/25/2021
SEONGCHAN PACK	03/25/2021
MING LIU	03/30/2021
RECEIVING PARTY DATA	
Name:	GM GLOBAL TECHNOLOGY OPERATIONS LLC
Street Address:	P.O. Box 300
Internal Address:	Mail Code 482-C23-B21
City:	Detroit
State/Country:	MICHIGAN
Postal Code:	48265-3000
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17225508
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	248-380-9300
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Correspondent Name:	QUINN IP LAW
Address Line 1:	21500 HAGGERTY ROAD, STE 300
Address Line 4:	NORTHVILLE, MICHIGAN 48167
ATTORNEY DOCKET NUMBER:	P054235-US-NP
NAME OF SUBMITTER:	DONNA BERKLEY
SIGNATURE:	/Donna Berkley/
DATE SIGNED:	04/08/2021
Total Attachments: 3	
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source=Assignment_P054235#page2.tif	
source=Assignment_P054235#page3.tif	

ASSIGNMENT

Pursuant to an agreement with my employer, I formally assign to GM GLOBAL TECHNOLOGY OPERATIONS LLC, the entire right, title, and interest, in all countries and in all application types, in the improvements set forth in the United States patent application for P054235-US-NP, which is entitled:

METAL-COATED, POLYMER-ENCAPSULATED ELECTRONICS MODULES AND
METHODS FOR MAKING THE SAME

and for which I executed a declaration. If the patent application has been filed, I authorize any practitioner associated with Customer No. 72823 to insert the application number and filing date of said application here in parentheses (17/225,508 filed 08-APRIL-2021) when known.

Inventor's signature:  Date 3/25/21
Full name: Anthony M. Coppola
Residence: Rochester Hills, Michigan 48309

Inventor's signature: _____ Date _____
Full name: Seongchan Pack
Residence: West Bloomfield, Michigan 48323

Inventor's signature: _____ Date _____
Full name: Ming Liu
Residence: Troy, Michigan 48085

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